

**APPENDIX A**

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**IN THE CLAIMS:**

A marked-up version of each of the presently amended claims, highlighting the changes thereto, follows:

22. (Four Times Amended) An electronic system comprising an input device, an output device, a memory device, and a processor device coupled to the input, output, and memory devices, at least one of the input, output, memory, and processor devices including an [integrated circuit] integrated circuit package comprising:

- a package body;
- an integrated circuit die positioned within the package body;
- a lead frame including a plurality of leads having portions enclosed within the package body that connect to the integrated circuit die, the plurality of leads having portions enclosed within the package body forming an area; and
- an electrically conductive heat sink positioned at least partially within the package body with a surface of a first portion of the heat sink facing the lead frame in close proximity to a substantial part of the enclosed portion of at least eighty percent of the area formed by the plurality of leads of the lead frame having portions enclosed within the package body forming an area and having a die-attach area on the surface of the first portion of the heat sink attached to the integrated circuit die, a second portion of the heat sink being opposite the die-attach area and projecting away from the first portion of the heat sink and the integrated circuit die.

24. (Four Times Amended) An [integrated circuit] integrated circuit package comprising:

- a package body;
- an integrated circuit die positioned within the package body;

a lead frame including a plurality of leads having portions enclosed within the package body that connect to the integrated circuit die, the plurality of leads having portions enclosed within the package body forming an area; and  
an electrically conductive heat sink positioned at least partially within the package body with a vertically extending columnar portion surrounded by a horizontally extending skirt portion having a lead frame attachment surface proximate a die-attach surface substantially vertically aligned with the columnar portion, the lead frame attachment surface being attached to the lead frame and extending in close proximity to a substantial part of the enclosed portions of at least eighty percent of the area formed by the plurality of leads of the lead frame having portions enclosed within the package body, the die-attach surface being attached to the integrated circuit die.

25. (Four Times Amended) An [integrated circuit] integrated circuit package comprising:  
an integrated circuit die;  
a lead frame including a plurality of leads having portions that are connected to the integrated circuit die, the plurality of leads forming an area; and  
an electrically conductive heat sink positioned having a surface of a first portion of the heat sink facing the lead frame in close proximity to a substantial part of an enclosed portion of at least eighty percent of the area formed by the plurality of leads of the lead frame and with a die-attach area on the surface of the first portion of the heat sink attached to the integrated circuit die, a second portion of the heat sink projecting away from the first portion of the heat sink under the die-attach area and the integrated circuit die, the heat sink coupled to one of a signal voltage and a reference voltage for the heat sink to operate respectively as a signal plane and a ground plane for the plurality of leads of the lead frame.